

RoHS

COMPLIANT HALOGEN

FREE Available

Vishay Siliconix

P-Channel 150-V (D-S) MOSFET

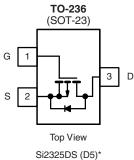
PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)		
- 150	1.2 at V _{GS} = - 10 V	- 0.69	7.7		
	1.3 at V _{GS} = - 6.0 V	- 0.66	7.7		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Available
- TrenchFET[®] Power MOSFET
- Ultra Low On-Resistance
- Small Size

APPLICATIONS

• Active Clamp Circuits in DC/DC Power Supplies



* Marking Code

Ordering Information: Si2325DS -T1-E3 (Lead (Pb)-free) Si2325DS -T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T	_A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 150		V
Gate-Source Voltage		V _{GS}	± 20		
	T _A = 25 °C	- I _D	- 0.69	- 0.53	
Continuous Drain Current $(T_J = 150 \ ^{\circ}C)^{a, b}$	T _A = 70 °C		- 0.55	- 0.43	
Pulsed Drain Current		I _{DM}	- 1.6		А
Continuous Source Current (Diode Conduction) ^{a, b}		ا _S	- 1.0	- 0.6	
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.5		
Single Pulse Avalanche Energy	L = 1.0 mH	E _{AS} 1.01		mJ	
M. S. D. S. S. ab	T _A = 25 °C	- P _D	1.25	0.75	W
Maximum Power Dissipation ^{a, b}	T _A = 70 °C		0.8	0.48	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum lumation to Ambienta	t ≤ 5 s	R _{thJA} R _{thJF}	75	100	
Maximum Junction-to-Ambient ^a	Steady State		120	166	°C/W
Maximum Junction-to-Foot (Drain)	Steady State		40	50	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.

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			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			•				
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V$, $I_D = -250 \mu A$	- 150			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 2.5	- 2.5 -			
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -150 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μΑ	
		V_{DS} = - 150 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \leq$ - 15 V, V_{GS} = 10 V	- 1.6			Α	
Drain-Source On-Resistance ^a	Б	$V_{GS} = -10$ V, $I_{D} = -0.5$ A		1.0	1.2	Ω	
	R _{DS(on)}	$V_{GS} = -6.0 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$		1.05	1.3		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$		2.2		S	
Diode Forward Voltage	V _{SD}	I _S = - 1.0 A, V _{GS} = 0 V		0.7	- 1.2	V	
Dynamic ^b	· · · · · ·						
Total Gate Charge	Qg	<u> </u>		7.7	12		
Gate-Source Charge	Q _{gs}	$V_{DS} = -75 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} \cong -0.5 \text{ A}$		1.5		nC	
Gate-Drain Charge	Q _{gd}			2.5			
Gate Resistance	R _g	f = 1.0 MHz		9		Ω	
Input Capacitance	C _{iss}			340	510	pF	
Output Capacitance	C _{oss}	V_{DS} = - 25 V, V_{GS} = 0 V, f = 1 MHz		30			
Reverse Transfer Capacitance	C _{rss}			16			
Switching ^c			·	·			
Turn-On Time	t _{d(on)}			7	11		
	t _r	V _{DD} = - 75 V, R _L = 75 Ω I _D ≅ - 1.0 A, V _{GEN} = - 10 V		11	17	ns	
Turn Off Time	t _{d(off)}	$R_{\rm g} = 6 \Omega$		16	25		
Turn-Off Time	t _f	- 'g - 0 - 0		11	17		
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 0.5 A, dl/dt = 100 A/μs		90	135	nC	

Notes:

a. Pulse test: PW \leq 300 μs duty cycle \leq 2 %.

b. For DESIGN AID ONLY, not subject to production testing.

c. Switching time is essentially independent of operating temperature.

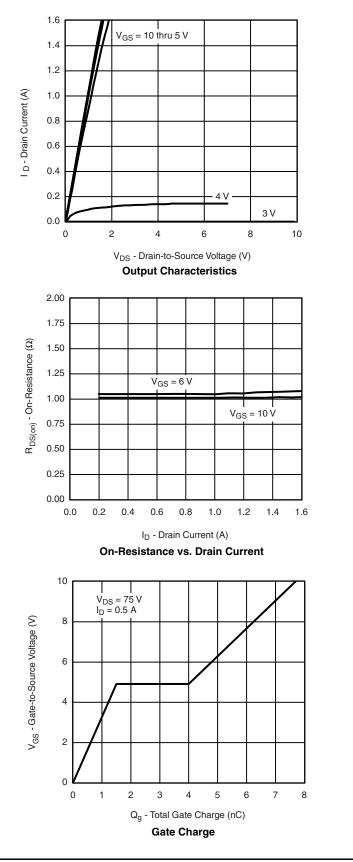
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

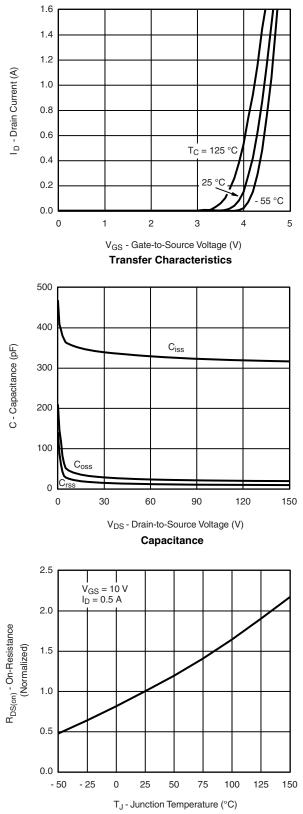


Si2325DS

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





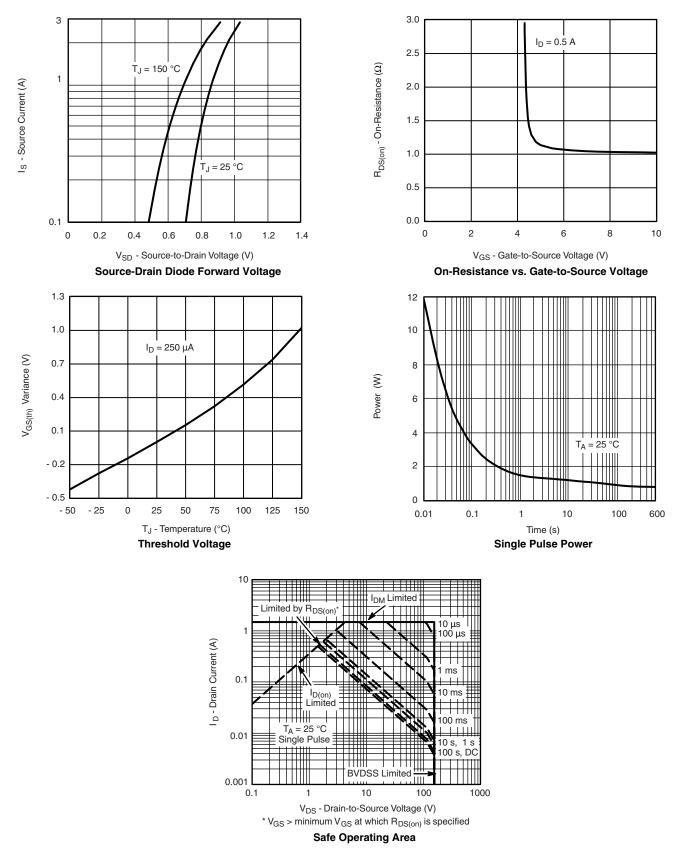
On-Resistance vs. Junction Temperature

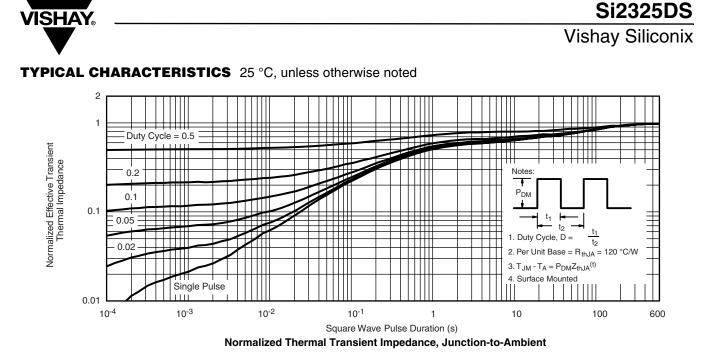
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?73238</u>.



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